MOSFETs Silicon P-Channel MOS (U-MOSVI)

# **TPCA8125**

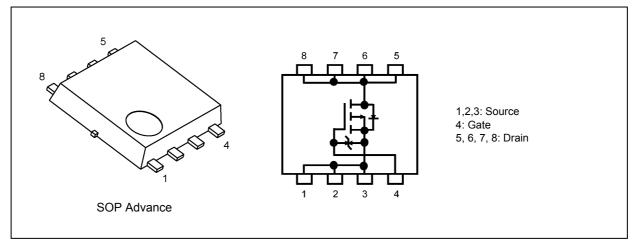
#### 1. Applications

- Motor Drivers
- Switching Voltage Regulators

#### 2. Features

- (1) Small, thin package
- (2) Low drain-source on-resistance:  $R_{DS(ON)} = 19.6 \text{ m}\Omega$  (typ.) (V<sub>GS</sub> = -10 V)
- (3) Low leakage current:  $I_{\rm DSS}$  = -10  $\mu A$  (max) (V\_{\rm DS} = -60 V)
- (4) Enhancement mode:  $V_{th}$  = -2.0 to -3.0 V ( $V_{DS}$  = -10 V,  $I_D$  = -1.0 mA)

#### 3. Packaging and Internal Circuit



#### 4. Absolute Maximum Ratings (Note) ( $T_a = 25^{\circ}C$ unless otherwise specified)

Characte	Symbol	Rating	Unit		
Drain-source voltage			V <sub>DSS</sub>	-60	V
Gate-source voltage			V <sub>GSS</sub>	-20/+10	
Drain current (DC)		(Note 1)	ID	-25	A
Drain current (pulsed)		(Note 1)	I <sub>DP</sub>	-75	
Power dissipation	(T <sub>c</sub> = 25°C)		PD	55	W
Power dissipation	(t = 10 s)	(Note 2)	PD	3.3	W
Power dissipation	(t = 10 s)	(Note 3)	PD	1.9	W
Single-pulse avalanche energy		(Note 4)	E <sub>AS</sub>	99	mJ
Avalanche current			I <sub>AR</sub>	-25	A
Channel temperature		(Note 5)	T <sub>ch</sub>	175	°C
Storage temperature			T <sub>stg</sub>	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production 2013-08 2014-02-28 Rev.2.0

#### 5. Thermal Characteristics

Characteristics				Max	Unit
Channel-to-case thermal resistance	(T <sub>c</sub> = 25°C)		R <sub>th(ch-c)</sub>	2.71	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 2)	R <sub>th(ch-a)</sub>	44.6	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	R <sub>th(ch-a)</sub>	78.1	°C/W

Note 1: Ensure that the channel temperature does not exceed 175°C.

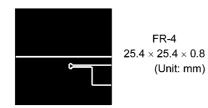
Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

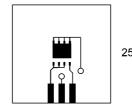
Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4: V<sub>DD</sub> = -25 V, T<sub>ch</sub> = 25°C (initial), L = 216  $\mu$ H, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = -25 A

Note 5: Merely channel temperature is guaranteed 175°C.

Storage temperature range is guaranteed as usual (-55 to 150°C).





FR-4 25.4 × 25.4 × 0.8 (Unit: mm)

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a) Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

#### 6. Electrical Characteristics

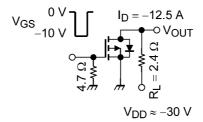
#### 6.1. Static Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = -16/+10 V, V <sub>DS</sub> = 0 V	_	_	±10	μA
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = -60 V, V <sub>GS</sub> = 0 V	—	_	-10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 0 V	-60		_	V
Drain-source breakdown voltage (Note 6)	V <sub>(BR)DSX</sub>	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 10 V	-50	_	_	
Gate threshold voltage	V <sub>th</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -1.0 mA	-2.0	_	-3.0	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = -6 V, I <sub>D</sub> = -12.5 A	—	21.5	34.4	mΩ
		V <sub>GS</sub> = -10 V, I <sub>D</sub> = -12.5 A	_	19.6	25.5	

Note 6: If a reverse bias is applied between gate and source, this device enters V<sub>(BR)DSX</sub> mode. Note that the drainsource breakdown voltage is lowered in this mode.

#### 6.2. Dynamic Characteristics ( $T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	3650	_	pF
Reverse transfer capacitance	C <sub>rss</sub>		_	260	—	
Output capacitance	C <sub>oss</sub>		_	320	_	
Switching time (rise time)	t <sub>r</sub>	See Figure 6.2.1.	_	6	_	ns
Switching time (turn-on time)	t <sub>on</sub>			17	_	
Switching time (fall time)	t <sub>f</sub>			34	_	
Switching time (turn-off time)	t <sub>off</sub>		_	165	_	



 $Duty \leq 1\%, \, t_W = 10 \ \mu s$  Fig. 6.2.1 Switching Time Test Circuit

#### 6.3. Gate Charge Characteristics ( $T_a = 25^{\circ}C$ unless otherwise specified)

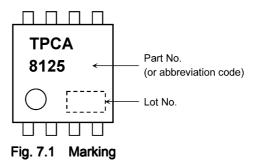
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx$ -48 V, $V_{GS}$ = -10 V, $I_D$ = -25 A	—	78	_	nC
Gate-source charge 1	Q <sub>gs1</sub>		_	11	_	
Gate-drain charge	Q <sub>gd</sub>			19		

#### 6.4. Source-Drain Characteristics ( $T_a = 25^{\circ}C$ unless otherwise specified)

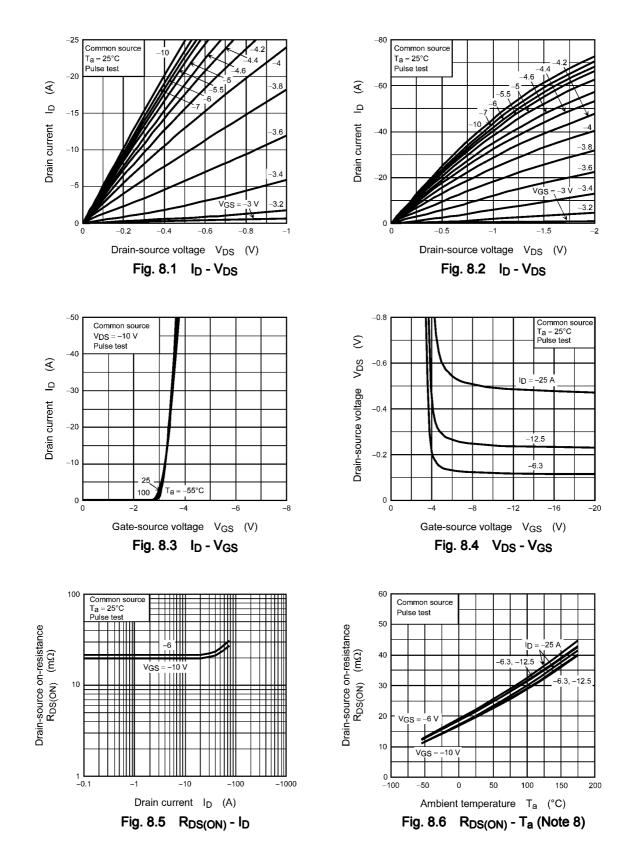
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed)	(Note 7)	I <sub>DRP</sub>	—	_	_	-75	А
Diode forward voltage		V <sub>DSF</sub>	I <sub>DR</sub> = -25 A, V <sub>GS</sub> = 0 V		_	1.2	V

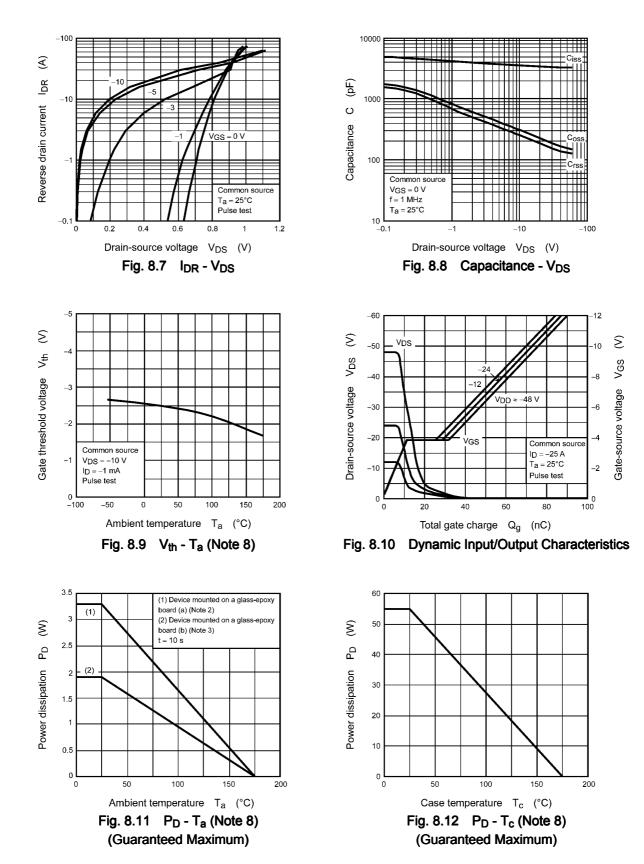
Note 7: Ensure that the channel temperature does not exceed 175°C.

7. Marking



#### 8. Characteristics Curves (Note)







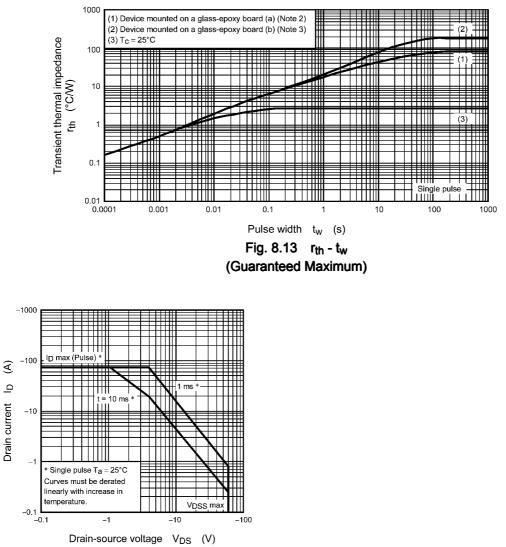


Fig. 8.14 Safe Operating Area (Guaranteed Maximum)

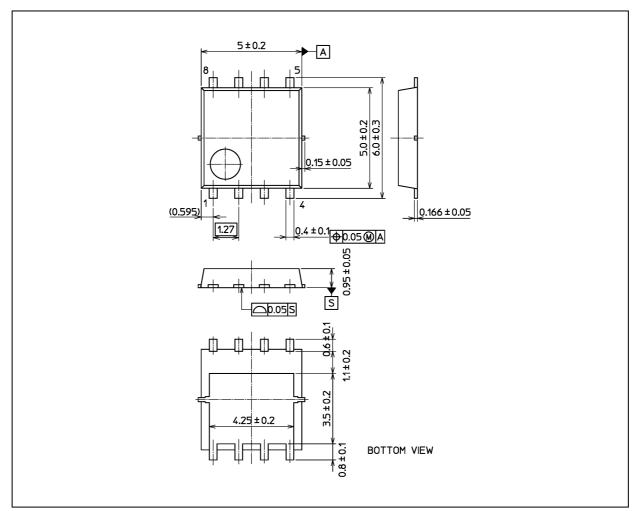
- Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.
- Note 8: Although several performance curves are shown up to a T<sub>a</sub> or T<sub>c</sub> of 175°C, the device is not guaranteed at storage temperatures up to 175°C. The storage temperature (T<sub>stg</sub>) range is rated at -55°C to 150°C.



### TPCA8125

#### Package Dimensions

Unit: mm



Weight: 0.069 g (typ.)

TOSHIBA: 2-5Q1S

Nickname: SOP Advance

Package Name(s)

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